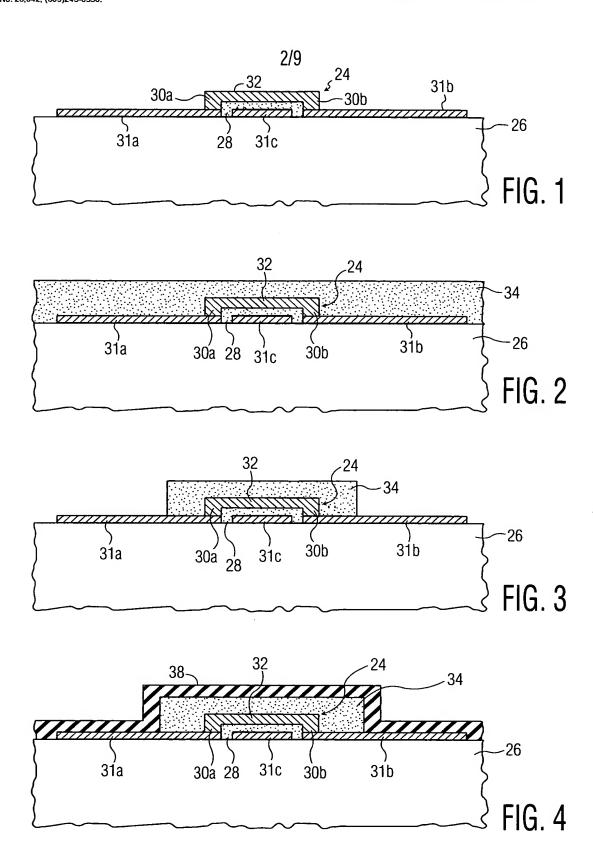
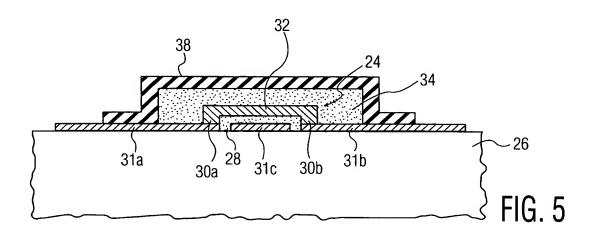


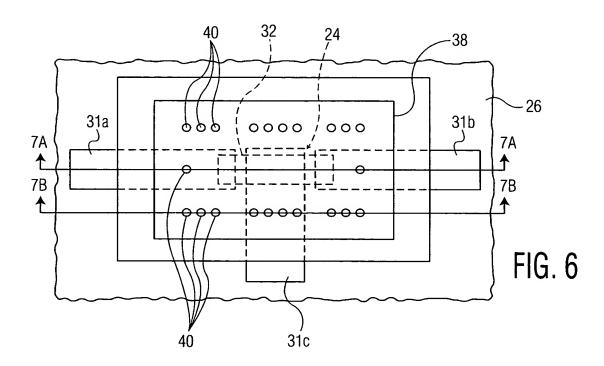
FIG. 1A

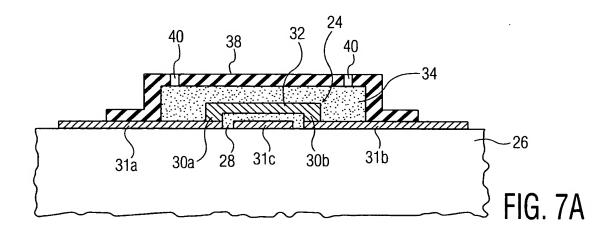


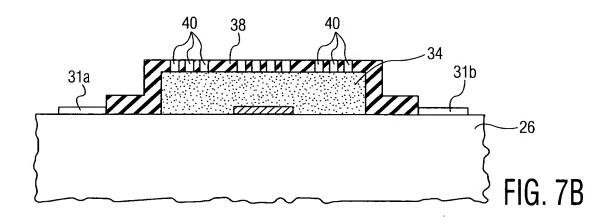
In re Application of:
Name of Inventor: Kin P. Cheung; Serial Number: (Unknown); Filing Date: (Unknown); Title of Invention: PROCESSES FOR HERMETICALLY PACKAGING WAFER LEVEL
MICROSCOPIC STRUCTURES; Examiner: (Unknown); Art Unit: (Unknown); Docket/Reference No.: 879.1.004; Attorney Name and Telephone Number: Kenneth Watov,
Reg. No. 26,042, (609)243-0330.



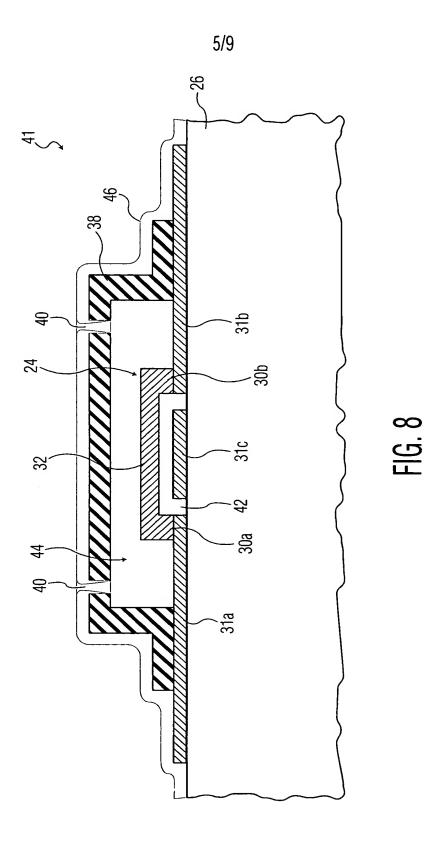




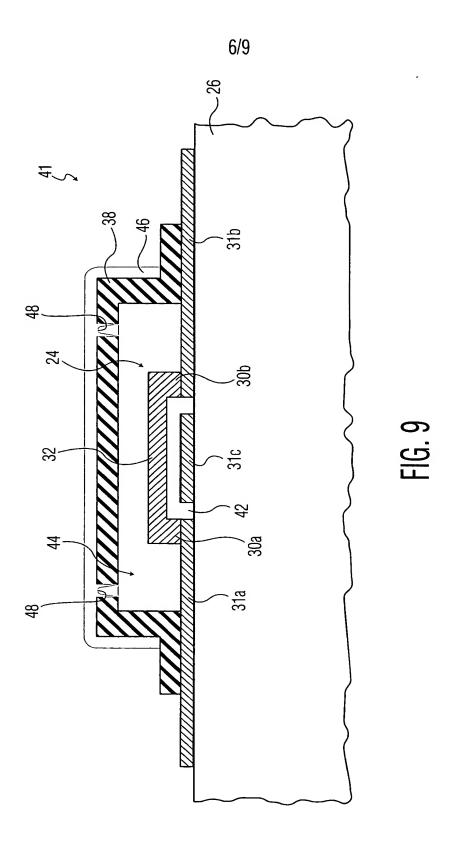


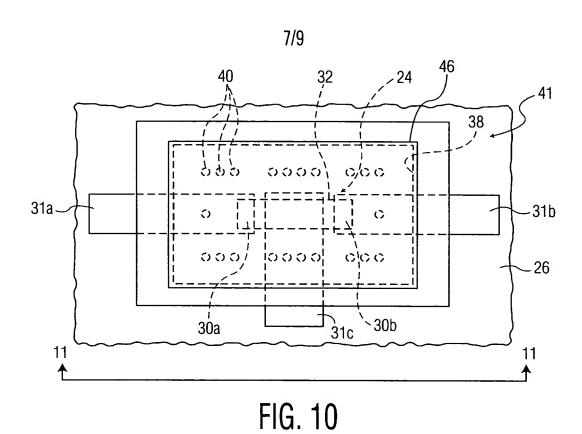


In re Application of:
Name of Inventor: Kin P. Cheung; Serial Number: (Unknown); Filing Date: (Unknown); Title of Invention: PROCESSES FOR HERMETICALLY PACKAGING WAFER LEVEL
MICROSCOPIC STRUCTURES; Examiner: (Unknown); Art Unit: (Unknown); Docket/Reference No.: 879.1.004; Attorney Name and Telephone Number: Kenneth Watov,
Reg. No. 26,042, (609)243-0330.



In re Application of:
Name of Inventor: Kin P. Cheung; Serial Number: (Unknown); Filing Date: (Unknown); Title of Invention: PROCESSES FOR HERMETICALLY PACKAGING WAFER LEVEL MICROSCOPIC STRUCTURES; Examiner: (Unknown); Art Unit: (Unknown); Docket/Reference No.: 879.1.004; Attorney Name and Telephone Number: Kenneth Watov, Reg. No. 26,042, (609)243-0330.





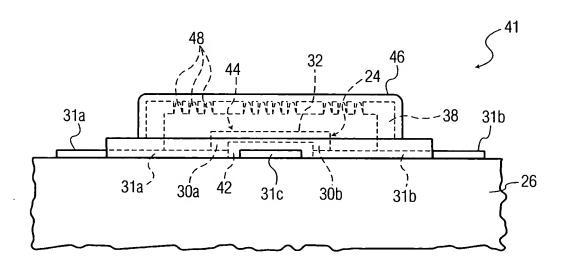


FIG. 11

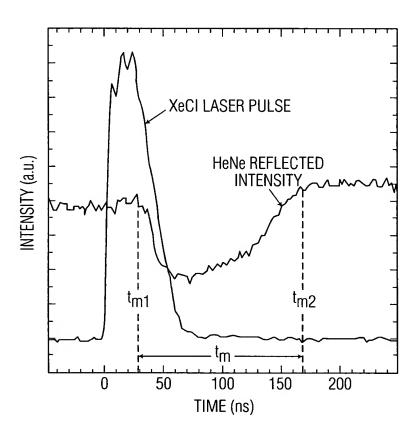


FIG. 12

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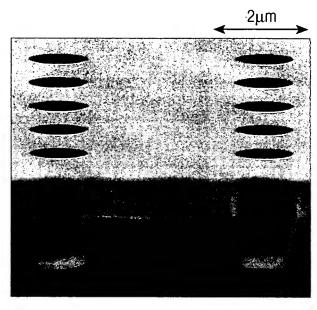


FIG. 13

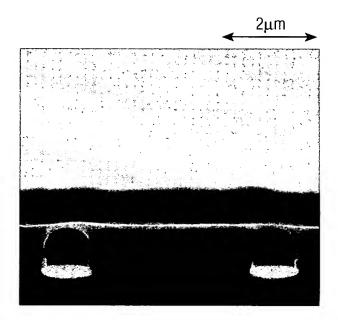


FIG. 14